

SAC305 LEAD-FREE SOLDER ALLOY

FEATURES

- Liquidus 220°C (428°F)
- Compatible with all Flux Types
- Excellent Wetting Speed
- Excellent Solderability and Spreading
- Reduced Bridging Versus Sn-Cu Alloys
- Manufactured with AIM Electropure™ Technology
- Complies with IPC J-STD-006

DESCRIPTION

SAC305 lead-free alloy contains 96.5 % tin, 3% silver, and 0.5% copper and is RoHS, REACH and JEIDA compliant. Applications include Wave, Selective, Hand and SMT Reflow Soldering. AIM Electropure™ SAC305 bar solder offers reduced dross production and superior wetting and fluidity as compared to other solder brands. AIM's SAC305 bar solder is alloyed using our proprietary Electropure™ method resulting in a low drossing, high wetting solder. AIM Electropure™ SAC305 may be used with all existing lead-free compatible equipment, processes, coatings, and flux chemistries.

AVAILABILITY

SAC305 is available in 1.1 kg (2.5 lb) triangular bars, hanging AIM Safety Bar and Solid Wire. SAC305 is also available in AIM flux cored wire solders and solder pastes.

TYPICAL ALLOY COMPOSITION

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Sn: Balance	Ag: 3.0	Cu: 0.5

TYPICAL MELTING TEMPERATURE

Typical Melting Temperature	
Solidus: 217°C (423°F)	Liquidus: 220°C (428°F)



HANDLING & STORAGE

Parameter	Time	Temperature
Shelf Life	Indefinite	Room Temperature

Indefinite shelf life applies to solid solder. For other product categories, refer to those specific TDSs. Consult AIM SAC305 SDS for additional handling procedures and precautions.

FLUX COMPATIBILITY

SAC305 bar solder is compatible with all major brands of no-clean and water soluble electronic grade fluxes.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.